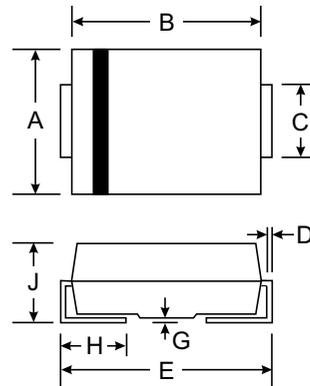
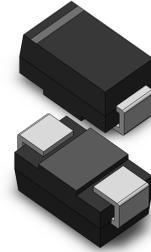


VOLTAGE RANGE: 20 - 40V
CURRENT: 1.0 A

Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O



SMA(DO-214AC)		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

Mechanical Data

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.064 grams (approx.)



Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SL12	SL13	SL14	Unit
Peak Repetitive Reverse Voltage	V _{RRM}				
Working Peak Reverse Voltage	V _{VRWM}	20	30	40	V
DC Blocking Voltage	V _R				
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	V
Average Rectified Output Current @T _L = 75°C	I _O	1.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30			A
Forward Voltage @I _F = 1.0A	V _{FM}	0.38	0.38	0.40	V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	0.5 20			mA
Typical Thermal Resistance Junction to Ambient (Note 1)	R _{θJA}	88			K/W
Operating Temperature Range	T _j	-65 to +125			°C
Storage Temperature Range	T _{STG}	-65 to +150			°C

Note: 1. Mounted on P.C. Board with 5.0mm² (0.13mm thick) copper pad areas

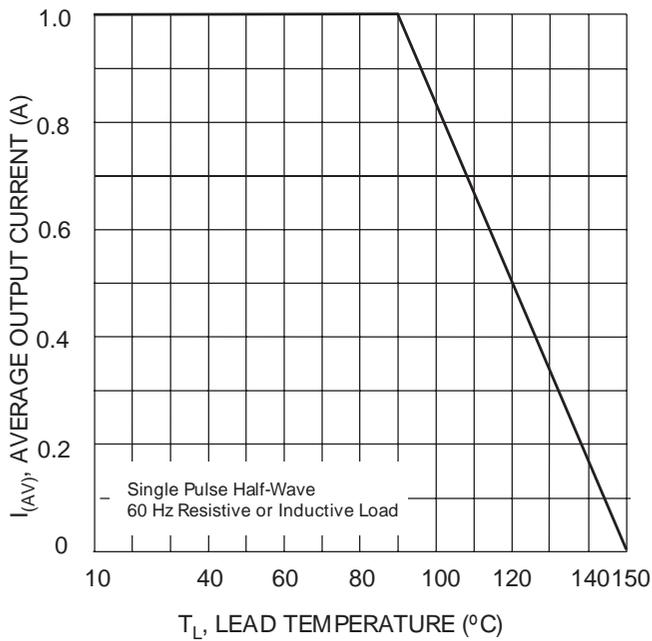


Fig. 1 Forward Current Derating Curve

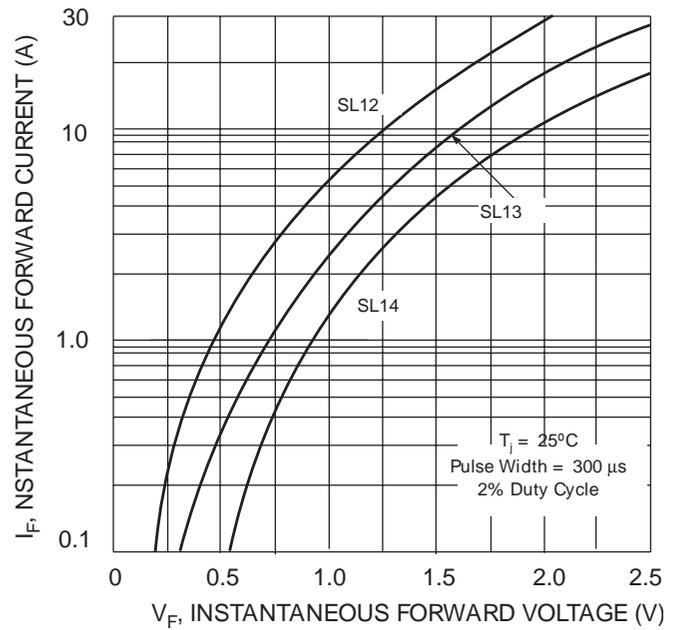


Fig. 2 Typical Forward Characteristics

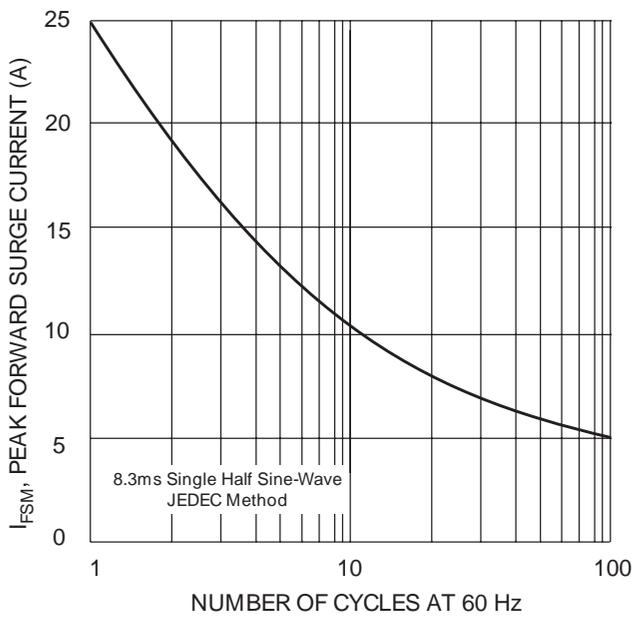


Fig. 3 Maximum Non-Repetitive Peak Fwd Surge Current

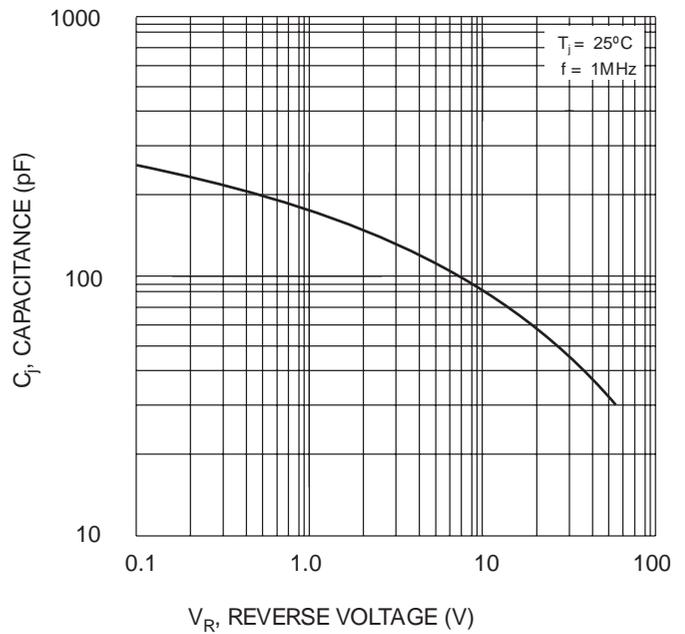


Fig. 4 Typical Junction Capacitance